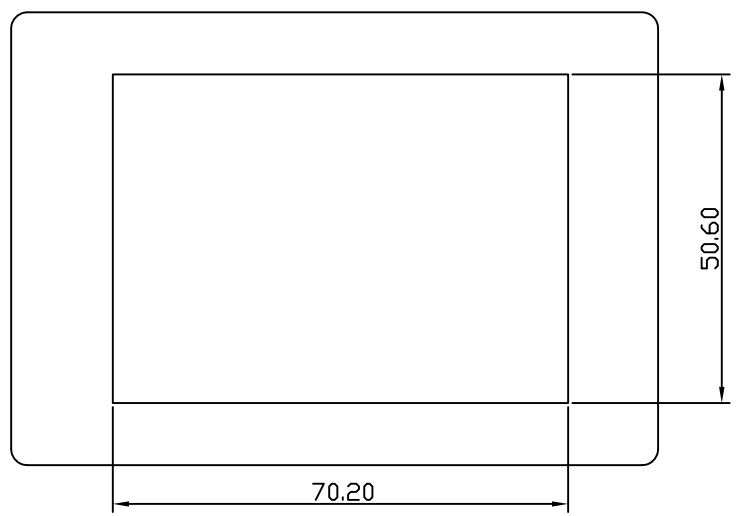
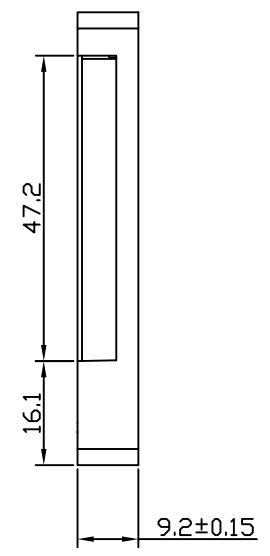
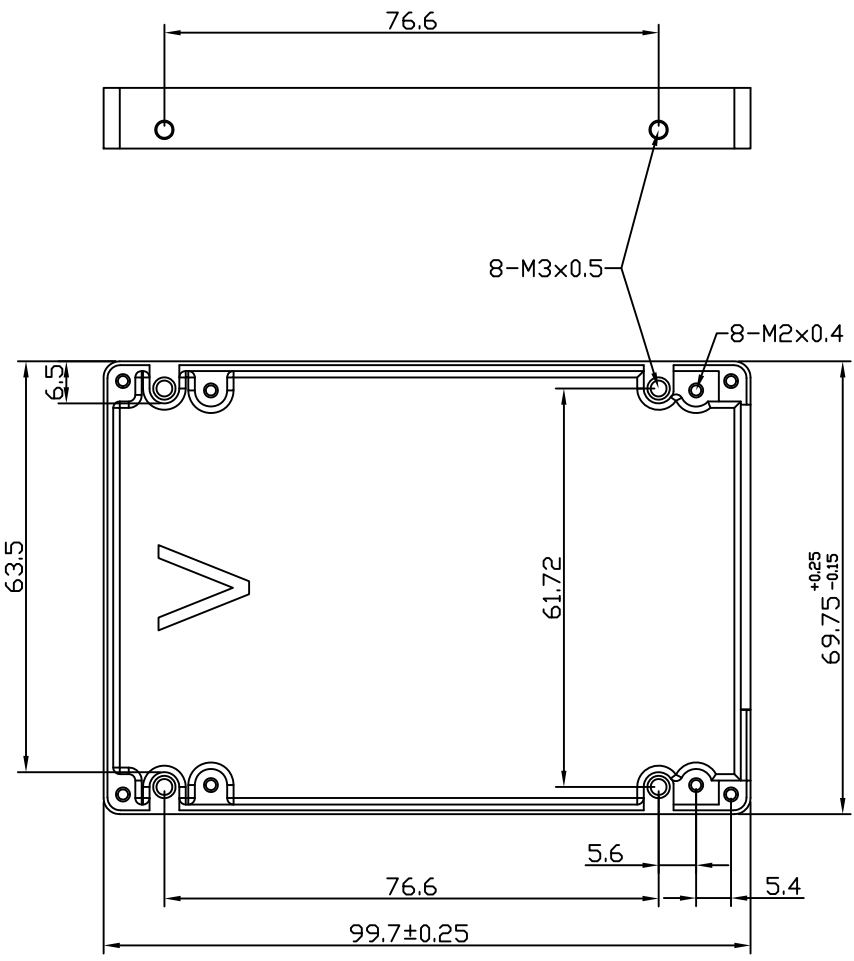
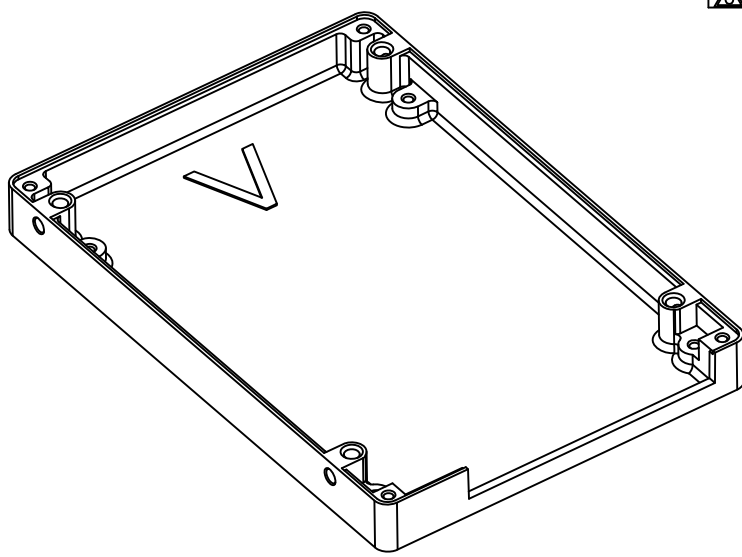


REV	11
	ECN

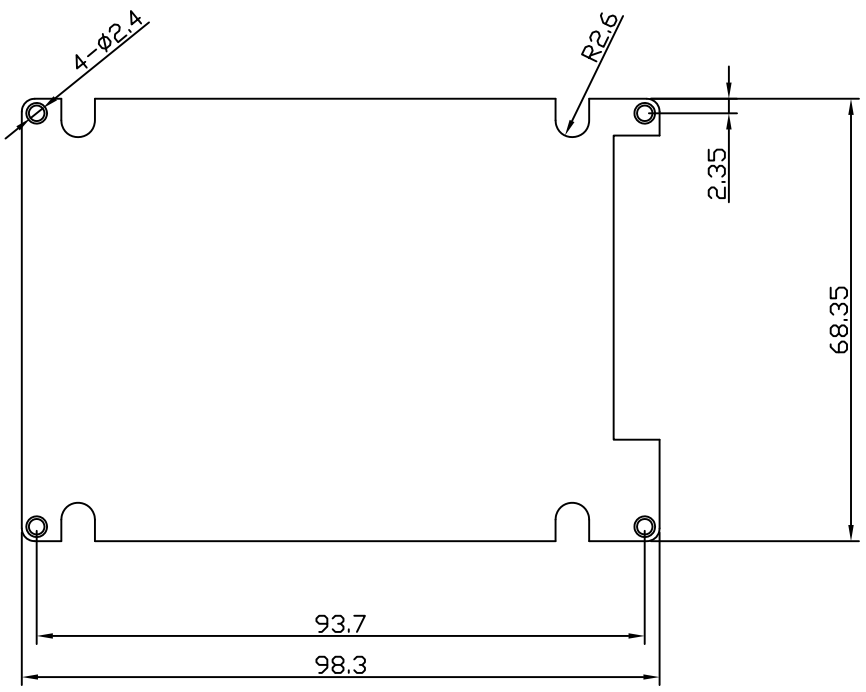


NOTES:

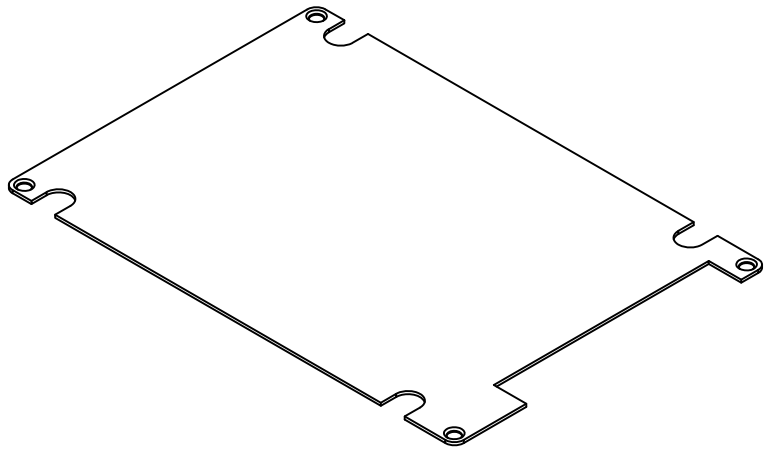
- 1.MATERIAL:AL-ADC 12
- 2.SURFACE TREATMENT:BLACK PAINTING
- 3.UNLESS SPECIFIED, THE TOLERANCE IS ± 0.25MM

UNIT	RATIO	EVERTRON	
MM			
TOLERANCE	AL	SSD CASE (bottom shell)	
X.X±			
X.XX±			
HOLE	DRAW: Hank	PART NUMBER	REV
ANGLE	CHECK:	CASE-BB03-1	△

REV	ECN
△	



剖面視圖A-A



- NOTES:
 1.MATERIAL:SUS
 2.SURFACE TREATMENT:BLACK PAINTING
 3.UNLESS SPECIFIED, THE TOLERANCE IS ± 0.25MM

UNIT	RATIO	EVERTRON	
MM			
TOLERANCE	SUS	SSD CASE (top shell)	
X.X±			
X.XX±			
HOLE	DRAW: Hank	PART NUMBER	REV
ANGLE	CHECK:	CASE-TB04-1	△

4 3 2 1

PART NO. SEE TABLE

REVISIONS			
LTR	DESCRIPTION	Drawing	DATE
A0	新產品發行	GARY	09/12/08

CUSTOMER DRAWING

剖面圖 A-A
比例 1:1

RECOMMENDED P.C. B LAYOUT
THICKNESS=1.04mm

剖面圖 B-B
比例 1:1

剖面圖 B-B
比例 1:1

TABLE 1

007-01-00703	GOLD FLASH	LCP BLACK	GP
007-01-00704	15 U" GOLD	LCP BLACK	GP
007-01-00705	30 U" GOLD	LCP BLACK	GP
PART NO.	PLATED	PLASTIC&COLOR	NOTE

NOTE:

- MATERIAL:
HOUSING:HIGH TEMPERATURE THERMOPLASTIC, UL94V-0, COLOR : SEE TABLE
TERMINAL:COPPER ALLOY,THICKNESS = 0.25 mm
- PLATING:
CONTACT:GOLD OVER 50u" MIN NICKEL UNDERPLATE
SOLDER TAIL:75u"MIN TIN 50u" MIN NICKEL UNDERPLATE
GOLD SPECIFICATION:SEE TABLE,
- ELECTRONICAL SPECIFICATION:
CURRENT RATING:1.5 AMPERE PER CONTACT
CONTACT RESISTANCE:30 MILLIOHMS MAX.
INSULATION RESISTANCE:1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING VOLTAGE:500 VDC.

DIMENSION ARE MILLIMETERS
TOLERANCES ARE :
DECIMALS
.X ± 0.30
.XX ± 0.25
ANGLE:
X ± 3°

APPROVALS		DATE
DRAWN	GARY	09/12/08
CHECKED		
APPROVALS		

EVERTRON			
TITLE: SATA 22P 公頭夾板式			
SIZE	SCALE :	DRAWING NO.	REV.
mm	1 : 1	000655	A0
ID NO.	XXXXXXXXXX	SHEET 1 OF 1	

NO	DESCRIPTION	Q'TY	UNIT	DO NOT SCALE DRAWING
4				
3				
2				
1				